

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method of bonding wire between first and second bonding points with a bonding tool, comprising, in the order stated, the steps of:

forming a first bond at the first bonding point with the bonding tool;
moving the bonding tool to a first position spaced from the first bond by a first distance;
moving the bonding tool from the first position towards the first bonding point and
applying a force on the first bond with the wire but without bonding forming a second
bond of the wire thereto;
moving the bonding tool to a second position spaced from the first bond by a second
distance;
forming a kink in the wire;
moving the bonding tool to extend a sufficient length of wire to form a wire loop between
the first and second bonding points; and
thereafter moving the bonding tool to the second bonding point and forming a second
bond.

2. (Currently Amended) A method according to claim 1, wherein:

the first position is substantially vertically above the first bonding point; and
~~the~~ the step of moving the bonding tool to the first position includes the steps of moving
the bonding tool substantially vertically upwards and thereafter moving the bonding tool towards
the second bonding point while keeping the bonding tool substantially vertically over the first
bond.

3. (Previously Presented) A method according to claim 1, wherein the step of moving the
bonding tool away from the first bond to the first position includes the steps of moving the

bonding tool substantially vertically upwards and thereafter moving the bonding tool away from the second bonding point.

4. (Original) A method according to claim 3, wherein the step of moving the bonding tool away from the second bonding point comprises moving the bonding tool in a curved motion to a point outside a vertical plane passing through the first and second bonding points.

5. (Previously Presented) A method according to claim 4, including the step of subsequently moving the bonding tool towards the first bonding point in a curved motion to a point on the vertical plane passing through the first and second bonding points before applying the force on the first bond with the wire.

6. (Previously Presented) A method according to claim 1, wherein the step of moving the bonding tool away from the first bond to the second position comprises the step of moving the bonding tool substantially vertically upwards.

7. (Original) A method according to claim 6, including the step of moving the bonding tool away from the second bonding point after moving the bonding tool vertically upwards.

8. (Previously Presented) A method according to claim 1, wherein the step of forming a kink in the wire comprises the steps of moving the bonding tool from the second position to a third position in a direction away from the second bonding point, then from the third position to a fourth position still further away from the second bonding point, and then from the fourth position back to the third position.

9. (Original) A method according to claim 1, wherein a diameter of the wire is approximately 1.0 mil or less and a height of a highest point on the bonded wire relative to the first bonding point is less than or equal to 2.35 times the diameter of the wire.

10.-13. (Canceled)

14. (Previously Presented) A wire loop including a wire bond comprising:
a ball-bonded base portion;
a curved portion integrated with and extending in an arc around at least a part of the base portion
which twists in a direction substantially around an axis that is substantially normal to a
bonding surface of the wire bond; and
a wire extending from the curved portion in a direction towards another wire bond.

15. (Original) A wire bond according to claim 14, wherein the curved portion of the wire loop has a substantially uniform cross-sectional area.

16. (Original) A wire bond according to claim 14, wherein the curved portion extends along at least a part of a perimeter of the base portion.

17. (Original) A wire loop according to claim 14, wherein a diameter of the wire is approximately 0.8 mils and a height of a highest point on the wire loop relative to a bottom of the base portion is less than or equal to 2.1 times the diameter of the wire.

18. (Original) A wire bond according to claim 14, wherein a diameter of the wire is approximately 1.0 mil and a height of a highest point on the wire loop relative to a bottom of the base portion is less than or equal to 2.0 times the diameter of the wire.